

Product Change Notification - JAON-23BSWK512

Date: 07 Apr 2015

Product Category: Supertex

Notification subject: CCB 1409.18 Final Notice - Additional Fabrication Site: Qualification of an additional fabrication site for DN1509, DN2530, DN2535, DN2540, DN2625, DN3135, DN3145, DN3525, DN3535 and DN3545 Supertex

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN_JAON-23BSWK512_Affected_CPN.xls

PCN_JAON-23BSWK512_Affected_CPN.pdf

Description of Change:

Qualification of an additional fabrication site for DN1509, DN2530, DN2535, DN2540, DN2625, DN3135, DN3145, DN3525, DN3535 and DN3545 Supertex device families.

Pre Change:

Fabricated at SPTX fab site.

Post Change:

Fabricated at Microchip FAB2 fab site.

Impacts to Data Sheet:

No

Reason for Change:

To improve productivity as part of the integration of Supertex and Microchip.

NOTE: SPTX will no longer have the ability to start additional wafers as of Q4 of CY14.

Change Implementation Status:

Complete

Estimated First Ship Date:

April 25, 2015 (date code: 1517)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

July 15, 2014: Issued initial notification as PCN number JAON-15TRYZ317.

August 14, 2014: Revised the initial notification by revising the CPN list to include all parts that are moving to FAB2, adding the note after the reason for change, and revising the customer letter to show that Supertex customers may register for Microchip's PCN email service.

April 07, 2015: Issued final notification. Attached the Qualification Report. Updated Impacts to Data Sheet from TBD to No. Revised the estimated first ship date from September 12, 2014 to April 25, 2015.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-23BSWK512_Qual_Report.pdf](#) [PCN_JAON-23BSWK512_Affected_CPN.pdf](#) [PCN_JAON-23BSWK512_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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PCN_JAON-23BSWK512
CATALOG_PART_NBR
DN1509K1-G
DN1509N8-G
DN2530N3-G
DN2530N8-G
DN2535N3-G
DN2535N3-G-P003
DN2535N3-G-P013
DN2535N5-G
DN2535ND
DN2540N3-G
DN2540N3-G-P003
DN2540N5-G
DN2540N8-G
DN2540NW
DN2625DK6-G
DN2625K4-G
DN3135K1-G
DN3135N8-G
DN3135NW
DN3145N8-G
DN3525N8-G
DN3525ND
DN3525NW
DN3535N8-G
DN3545N3-G
DN3545N8-G
DN3545N8-G-D561
DN3545ND
DN3545ND-D560
DN3545ND-D561



PCN #: JAON-23BSWK512

**Date:
March 24, 2015**

**Qualification of an additional fabrication site for DN1509,
DN2530, DN2535, DN2540, DN2625, DN3135, DN3145,
DN3525, DN3535 and DN3545 Supertex device families**

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QUALIFICATION DATA

High Temperature Operating Life: High Temperature Reverse Bias (HTRB)

Test Method	Mil-STD 750, M1042, Condition A ^{a b}
Test Condition	150°C / 1000 hours
Sample Size (45 ea. min)	(Fail/Pass)
Lot 1	0/45 ^c

^a Max rated Bvdss used as the drain bias

^b Gate to source voltage = -5V

^c Pre & Post testing was conducted at room temperature, ~25°C.

High Temperature Operating Life: High Temperature Gate Bias (HTGB)

Test Method	Mil-STD 750, M1042, Condition B ^a
Test Condition	150°C / 1000 hours
Sample Size (45 ea. min)	(Fail/Pass)
Lot 1	0/45 ^b

^a Max rated Bvgss used as the gate bias

^b Pre & Post testing was conducted at room temperature, ~25°C.

ESD

Test	Domain	Reference Method	Sample Size	Result
ESD – HBM	Gate to Source	Class 0 as per the Mil-Std 750 M1020	Lot 1 = 9ea	+/-110V ^a
ESD – HBM	Gate to Drain	Class 0 as per the Mil-Std 750 M1020	Lot 1 = 9ea	+/-110V ^a
ESD – HBM	Gate to Drain/Source	Class 0 as per the Mil-Std 750 M1020	Lot 1 = 9ea	+/-110V ^a
ESD – HBM	Drain to Gate/Source	Class 0 as per the Mil-Std 750 M1020	Lot 1 = 6ea	+/-1100V ^a

^a Pre & Post testing was conducted at room temperature, ~25°C.